



Intel® Core™ i3-2370M Processor
(3M Cache, 2.40 GHz)

Compare +

Specifications

Essentials

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Advanced Technologies

Intel® Data Protection Technology

Intel® Platform Protection Technology

Ordering / sSpecs / Steppings

Essentials

Status

Launched

Launch Date

Q1'12

Processor Number

i3-2370M

Intel® Smart Cache

3 MB

DMI

5 GT/s

Instruction Set

64-bit

Instruction Set Extensions

AVX

Embedded Options Available

No

Lithography

32 nm

Recommended Customer Price

TRAY: \$225.00

Datasheet

Link

Performance

of Cores

2

of Threads

4

Processor Base Frequency

2.4 GHz

TDP

35 W

Memory Specifications

Max Memory Size (dependent on memory type)

16 GB

Memory Types

DDR3 1066/1333

Max # of Memory Channels

2

Max Memory Bandwidth

21.3 GB/s

ECC Memory Supported *

No

Graphics Specifications

Processor Graphics *

Intel® HD Graphics 3000

Graphics Base Frequency

650 MHz

Graphics Max Dynamic Frequency

1.15 GHz

Graphics Output

eDP/DP/HDMI/SDVO/CRT

Intel® Quick Sync Video

Yes

Intel® InTru™ 3D Technology

Yes

Intel® Insider™

Yes

Intel® Wireless Display

Yes

Intel® Flexible Display Interface (Intel® FDI)

Yes

Intel® Clear Video HD Technology

Yes

Macrovision* License Required

No

of Displays Supported *

2

Expansion Options

PCI Express Revision

2.0

PCI Express Configurations *

1x16, 2x8, 1x8 2x4

Max # of PCI Express Lanes

16

Package Specifications

Max CPU Configuration

1

T_{JUNCTION}

85C (PGA); 100C (BGA)

Package Size

37.5mm x 37.5mm (rPGA988B); 31mm x 24mm (BGA1023)

Graphics and IMC Lithography

32 nm

Sockets Supported

PPGA988

Low Halogen Options Available

See MDDS

Advanced Technologies

Intel® Turbo Boost Technology *

No

Intel® vPro Technology *

No

Intel® Hyper-Threading Technology *

Yes

Intel® Virtualization Technology (VT-x) *

Yes

Intel® Virtualization Technology for Directed I/O (VT-d) *

No

Intel® VT-x with Extended Page Tables (EPT) *

Yes

Intel® 64 *

Yes

Intel® My WiFi Technology

Yes

4G WiMAX Wireless Technology

Yes

Idle States

Yes

Enhanced Intel SpeedStep® Technology

Yes

Intel® Demand Based Switching

No

Thermal Monitoring Technologies

Yes

Intel® Fast Memory Access

Yes

Intel® Flex Memory Access

Yes

Intel® Identity Protection Technology *

Yes

Intel® Data Protection Technology

AES New Instructions

No

Intel® Platform Protection Technology

Trusted Execution Technology *

No

Execute Disable Bit *

Yes

Anti-Theft Technology

Yes

Related Products

2nd Generation Intel® Core™ i3 Processors

Intel® Core™ i3-2300 Mobile Processor Series

Products formerly Sandy Bridge

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PCN/MDDS Information

SR0DP

916670: PCN | MDDS

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Refer to Datasheet for formal definitions of product properties and features.

"Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.

Some products can support AES New Instructions with a Processor Configuration update, in particular, i7-2630QM/i7-2635QM, i7-2670QM/i7-2675QM, i5-2430M/i5-2435M, i5-2410M/i5-2415M. Please contact OEM for the BIOS that includes the latest Processor configuration update.

* This feature may not be available on all computing systems. Please check with the system vendor to determine if your system delivers this feature, or reference the system specifications (motherboard, processor, chipset, power supply, HDD, graphics controller, memory, BIOS, drivers, virtual machine monitor-VMM, platform software, and/or operating system) for feature compatibility. Functionality, performance, and other benefits of this feature may vary depending on system configuration.

"Conflict free" and "conflict-free" means "DRC conflict free", which is defined by the U.S. Securities and Exchange Commission rules to mean products that do not contain conflict minerals (tin, tantalum, tungsten and/or gold) that directly or indirectly finance or benefit armed groups in the Democratic Republic of the Congo (DRC) or adjoining countries. Intel also uses the term "conflict-free" in a broader sense to refer to suppliers, supply chains, smelters and refiners whose sources of conflict minerals do not finance conflict in the DRC or adjoining countries. Intel processors manufactured before January 1, 2013 are not confirmed conflict free. The conflict free designation refers only to product manufactured after that date. For Intel Boxed Processors, the conflict free designation refers to the processor only, not to any additional included accessories, such as heatsinks/coolers.

See <http://www.intel.com/content/www/us/en/architecture-and-technology/hyper-threading/hyper-threading-technology.html?wapkw=hyper+threading> for more information including details on which processors support Intel® HT Technology.

Max Turbo Frequency refers to the maximum single-core processor frequency that can be achieved with Intel® Turbo Boost Technology. See www.intel.com/technology/turboboost/ for more information.

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System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used.

Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Intel components as well as purchased components on the finished assembly meet JS-709 requirements, and the PCB / substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment.

For benchmarking data see <http://www.intel.com/performance>.

Intel processor numbers are not a measure of performance. Processor numbers differentiate features within each processor family, not across different processor families. See <http://www.intel.com/content/www/us/en/processors/processor-numbers.html> for details.

Processors that support 64-bit computing on Intel® architecture require an Intel 64 architecture-enabled BIOS.

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